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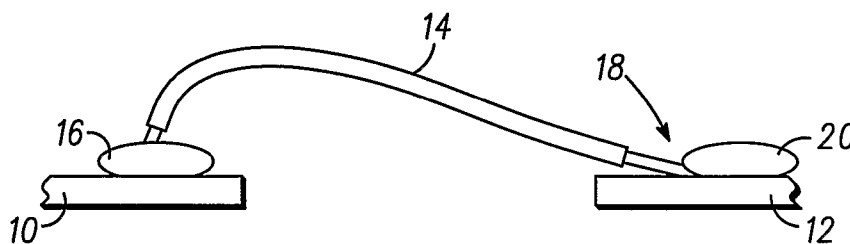
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(54) Title: WIREBONDING INSULATED WIRE



(57) Abstract: An electrical con-
nection for connecting a bond pad
of a first device and a bond pad of
a second device with an insulated
or coated wire. The electrical con-
nection includes a first wirebond
securing a first portion of the insu-
lated bond wire to the first device
bond pad. A second wirebond se-
cures a second portion of the insu-
lated bond wire to the second de-

vice bond pad. A bump is formed over the second wirebond, and the bump is offset from the second wirebond. The offset bump
enhances the second bond, providing it with increased wire peel strength.

WO 2004/075347 A2